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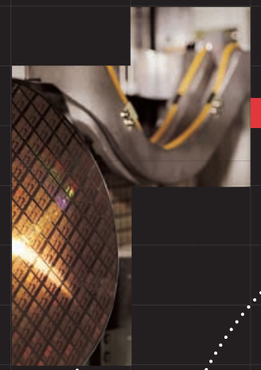

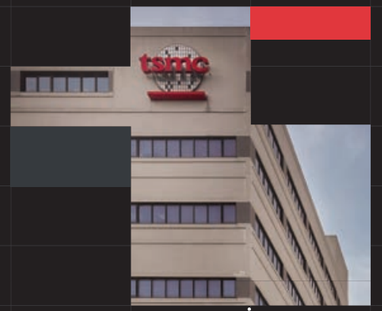

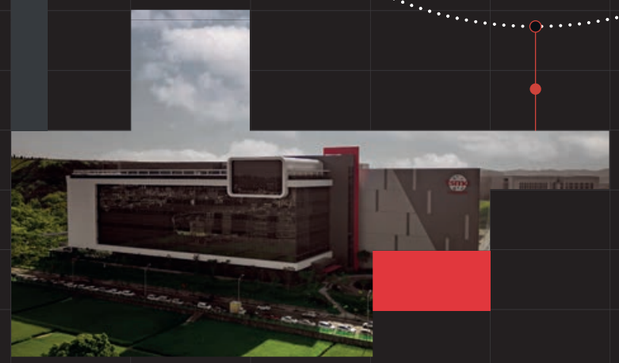

2

Company Profile

TSMC’s total wafer shipments were 15 million 12-inch equivalent wafers in 2025.

2.1 An Introduction to TSMC

Established in 1987 and headquartered in Hsinchu Science Park, Taiwan, TSMC pioneered the pure-play foundry business model with an exclusive focus on manufacturing its customers' products. By choosing not to design, manufacture or market any semiconductor products under its own name, the Company ensures that it never competes with its customers. Based on this founding principle, the key to TSMC's success has always been to enable its customers' success. TSMC's foundry business model has led to the rise of the global fabless industry and, since its inception, TSMC has been a world-leading semiconductor foundry. In 2025, the Company manufactured 12,682 different products using 305 distinct technologies for 534 different customers.

TSMC-made semiconductors serve a global customer base that is large and diverse, entailing a wide range of applications. The Company's semiconductor products are used in a variety of end markets including high performance computing (HPC), smartphones, the Internet of Things (IoT), automotive, and digital consumer electronics. Such strong diversification helps to smooth fluctuations in demand, which in turn allows TSMC to maintain high levels of capacity utilization and profitability, and generate healthy returns for future investment.

The annual capacity of the manufacturing facilities managed by TSMC and its subsidiaries exceeded 17 million 12-inch equivalent wafers in 2025. These facilities include four 12-inch wafer GIGAFAB® fabs, four 8-inch wafer fabs, and one 6-inch wafer fab – all in Taiwan – as well as two 12-inch wafer fabs at two wholly owned subsidiaries – TSMC Nanjing Company Limited and TSMC Arizona Corporation – one 12-inch wafer fab at a TSMC's majority-owned manufacturing subsidiary – Japan Advanced Semiconductor Manufacturing, Inc. (JASM) – and two 8-inch wafer fabs at two wholly owned subsidiaries – TSMC Washington and TSMC China Company Limited.

TSMC Arizona's first facility began volume production of 4nm technology in fourth quarter of 2024. The construction of the second facility has been completed and it is in the process of installing facility systems to produce 3-nanometer and more advanced technologies. In 2025, TSMC Arizona started construction of a third facility. Also in 2025, TSMC announced its intention to expand its investment in advanced semiconductor manufacturing in the United States, including plans for three additional fabrication plants, two advanced packaging facilities and a major R&D team center.

JASM started volume production in its first facility at the end of 2024 and began construction of a second facility in 2025. With both fabs, JASM's Kumamoto site plans to offer 40, 22/28, 12/16, 6/7 and 3 nanometer process technologies for automotive, industrial, consumer electronics and HPC-related applications.

The Company began construction of a specialty technology fab in Dresden, Germany, in 2024. This facility will manufacture TSMC's 28/22 nanometer planar CMOS and 16/12 nanometer FinFET process technologies.

Outside of Taiwan, TSMC provides customer support, account management and engineering services through its offices in North America, Europe, Japan, China, and South Korea. At the end of 2025, the Company and its subsidiaries employed more than 90,000 people worldwide.

The Company is listed on the Taiwan Stock Exchange (TWSE) under ticker number 2330, and its American Depositary Shares (ADSs) are traded on the New York Stock Exchange (NYSE) under the symbol TSM.

2.2 Market/Business Summary

2.2.1 TSMC Achievements

The Company's strong market position stems in great part from its leadership in advanced process technologies. In 2025, 74% of TSMC's wafer revenue came from advanced manufacturing processes – defined as geometries of 7nm and smaller – up from 69% in 2024.

TSMC offers a comprehensive technology portfolio and continues to expand its advanced technologies, specialty technologies, and advanced silicon stacking and packaging technologies, to meet customer demand and provide more added value.

In addition to its leadership in advanced process and specialty technologies, TSMC offers TSMC 3DFabric®, a comprehensive family of 3D silicon stacking and advanced packaging solutions to complement its process technology offerings. TSMC 3DFabric® solutions provide customers greater chip design flexibility to unleash innovation and is another differentiating competitive advantage for the Company.

2.2.2 Market Overview

TSMC estimates that the worldwide semiconductor market excluding memory reached US$611 billion in revenue in 2025, representing a 19% increase from 2024. As for the foundry sector, the Company has expanded the original definition to Foundry 2.0, which now also includes packaging, testing, mask-making, and other related technologies, as well as all integrated device manufacturing (IDMs) excluding memory. Going forward all references to the foundry segment will use the new Foundry 2.0 definition as it more accurately reflects TSMC's addressable market opportunities. The size of this foundry sector is estimated to have reached US$305 billion in 2025, representing 16% growth from 2024.

2.2.3 Industry Outlook, Opportunities and Threats

Foundry Industry Demand and Supply Outlook

In 2025, TSMC's revenues in the foundry segment further accelerated following a strong rebound in 2024. AI deployments remained strong throughout the year, driving robust demand for advanced node semiconductor chips and benefitting foundry players like TSMC with leadership positions in both advanced process technologies and advanced packaging technologies. In addition, end demand for smartphones and personal computers were healthy, while other markets such as the Internet of Things (IoT), automotive and industrial also recovered from the inventory correction cycle in 2023 and 2024.

Looking ahead to 2026, global trade conflicts and protectionism persist, presenting risks and uncertainties to the end demand of electronic equipment. Nonetheless, TSMC expects the strong demand for AI to continue, while other non-AI markets are expected to be softer. The Company also anticipates continued strong demand for advanced nodes and advanced packaging. In mature technologies, overall demand is expected to improve with post-inventory digestion, though increased capacity, especially in China, will challenge non-China foundries, including TSMC. For the longer term, driven by the megatrends of AI, 5G/6G, digital transformation and increasing semiconductor content in most electronic equipment, TSMC projects approximately 10% compound annual growth for the worldwide semiconductor market excluding memory through 2030.

As an upstream supplier in the semiconductor supply chain, the foundry segment is tightly correlated with the market health of all major end markets including high performance computing (HPC), smartphones, IoT, automotive, and digital consumer electronics (DCE).

- High Performance Computing (HPC)

The HPC platform includes PCs, tablets, game consoles, servers, base stations and more. Major HPC unit shipments grew by 9% in 2025 driven by PC upgrades and strong commercial demand, the introduction of new game console models, and most importantly, the continued strong momentum for AI-equipped servers and data centers, spurred by the proliferation of AI applications, especially generative AI.

For 2026, TSMC projects a decline for PCs but low teens growth for server shipments, driven by the intensifying AI arms race. Longer term, a more intelligent, more connected world will create greater demand for massive computing power as well as increasingly energy-efficient computing. Both trends require higher performance and more power-efficient central processing units (CPUs), graphics processing units (GPUs), network processing units (NPUs), and AI-related, application-specific integrated circuits (ASICs), all of which will drive the overall HPC platform towards richer silicon content, more advanced process technologies and advanced 3D packaging. These trends are all favorable to TSMC given its technological leadership in each of these areas.

- Smartphones

The smartphone market showed continued growth in 2025, with unit shipment up around 3%. This moderate increase is primarily attributable to continued 5G commercialization globally, rising demand from emerging countries, as well as sustained cyclical replacement demand. The subsidy program in China also boosted the smartphone sales. Looking ahead to 2026, smartphone growth is anticipated to decline reflecting the negative impact of memory shortage and price increases. Nevertheless, the long-term outlook remains positive, as the continued transition to 5G, along with the constant demand for improved performance, longer battery life, advanced biosensors and expanded edge AI features, will collectively fuel sustained smartphone growth.

High performance and power efficient IC technologies are essential requirements for handset manufacturers. Highly integrated chips and advanced packaging designs are the

preferred solutions for optimizing cost, power and form factors (IC footprint and thickness). The imperative for higher performance chips, which are essential for executing edge AI applications, performing complex software computations, and managing high-resolution images and video, will continue to drive the adoption of advanced technologies. As an acknowledged leader in process technology for manufacturing highly integrated chips and advanced packaging designs, TSMC is exceptionally well-positioned to serve the evolving needs of the smartphone market.

• Internet of Things (IoT)

The IoT market rebounded from a sluggish 2024 to achieve 11% unit shipment growth in 2025. The increase was broad based and included personal connected devices such as wearables (e.g. AI glasses and smartwatches), smart homes (smart appliances with edge AI capability), smart cities, and industrial IoT applications (smart retails, energy monitoring and manufacturing automation). This healthy growth momentum is expected to continue into 2026 with high single digit growth. For the longer term, as more AI connectivity and interoperability features are integrated into IoT devices, the overall IoT market is expected to continue experiencing high unit growth.

The increasing AI integration and power efficiency demands of IoT devices drive the need for high-performance, low-power chips. TSMC meets these evolving requirements through its comprehensive portfolio of manufacturing processes, including cost-effective advanced technology and industry-leading ultra-low power (ULP) technologies to support customers' product innovations for the artificial intelligence of things (AIoT).

• Automotive

The automotive market experienced a healthy recovery in 2025, with global unit production rising 3%. This growth was primarily supported by government subsidy programs and pre-emptive purchases spurred by tariff uncertainties. For 2026, TSMC projects flat to slight decline in car unit production and anticipates a challenging environment due to macroeconomic uncertainties and the diminishing impact of subsidies and pull-in purchases.

For the longer term, the automotive megatrends of "greener, safer and smarter" will continue to accelerate the adoption of electric vehicles (EVs), advanced driver assistance systems (ADAS) and smart cockpit/infotainment systems. These increasingly sophisticated systems will further boost demand for application processor (AP), microcontroller unit (MCU), in-car networking, sensors, and power management ICs (PMICs), thereby continuously increasing the silicon content per car. TSMC is uniquely positioned to support the automotive industry's transition by providing advanced process technologies and manufacturing solutions that enable customers to develop highly competitive products. In addition, TSMC also offers a range of automotive-grade manufacturing processes, including those with AEC-Q100 and ISO 26262 certification, to ensure the highest levels of quality and reliability for automotive applications.

• Digital Consumer Electronics (DCE)

The overall DCE market contracted slightly in 2025. Persistent structural headwinds, including evolving consumer behavior, shifts in screen time allocation, and the increasing integration of functions into mobile products, depressed demand for several major DCE products such as set-top boxes (STBs) and digital still cameras (DSCs). Digital TV shipments, another key DCE product, remained largely flat, partly due to a pull-in effect from China's subsidy program initiated in the second half of 2024.

Moving to 2026, although major sporting events such as the FIFA World Cup and Winter Olympics may stimulate DTV and STB demand to some extent, the overall DCE market is projected to be flat to down slightly due to persistent structural headwinds and an unfavorable memory pricing environment. Despite this soft market, TSMC's advanced process technologies will remain crucial, enabling its customers to develop distinctive and innovative products.

Supply Chain

The electronics industry features a long and complex supply chain, the elements of which are correlated and highly interdependent. At the upstream manufacturing level, IC vendors need to have sufficient and flexible supply deliveries to cope with fluctuating demand dynamics. Foundry vendors play an important role in maintaining the health and effectiveness of the supply chain. As a leader in the foundry segment, TSMC provides advanced technologies and large-scale capacity to complement the innovations created in the downstream chain.

2.2.4 TSMC Position, Differentiation and Strategy

Position

TSMC is a global semiconductor foundry leader in advanced and specialty technologies as well as advanced packaging technologies. In 2025, the Company accounted for 40% of the Foundry 2.0 industry. This was an increase from 34% in 2024. Net revenue by geography, calculated mainly on the country in which customer companies are headquartered, was: 75% from North America; 9% from the Asia Pacific region excluding China and Japan; 9% from China; 4% from Japan; and 3% from Europe, the Middle East and Africa. Net revenue by platform was: 58% HPC; 29% smartphones; 5% the IoT; and 5% automotive. In addition, 1% came from DCE, while other segments accounted for the remaining 2%.

Differentiation

TSMC's leadership position is based on three defining competitive strengths and a business strategy deeply rooted in its heritage. The Company distinguishes itself through its unwavering focus on technology leadership, manufacturing excellence, and customer trust.

As a technology leader, TSMC is consistently first among dedicated foundries to provide leading-edge, next-generation technologies. The Company also maintains a leadership position in more mature technologies by applying the lessons learned in developing advanced technologies to enrich its specialty technologies. Beyond process technology, TSMC has established frontend and backend integration capabilities including packaging, testing, and advanced system integration, to create the optimum power, performance, and area (PPA) "sweet spot" to help customers achieve faster time-to-production.

Widely recognized for its industry-leading manufacturing capabilities, TSMC's leadership is further enhanced through its Open Innovation Platform® collaboration alliance and Grand Alliance initiatives. The Company's Open Innovation Platform® collaboration alliance initiative accelerates the pace of innovation in the semiconductor design community and among the Company's ecosystem partners, as well as in its own IP, design-technology co-optimization (DTCO) capabilities, advanced process technology, and system-technology co-optimization (STCO) with advanced packaging services. A key element to this is a set of ecosystem interfaces and collaborative components initiated and supported by the Company to more efficiently empower innovation throughout the supply chain. The TSMC Grand Alliance is one of the most powerful forces for innovation in the semiconductor industry, bringing together customers, providers of electronic design automation (EDA) tools, IP's, design services and cloud infrastructure, and partners in the TSMC 3DFabric® alliance, which also includes equipment and material suppliers – all to achieve new, higher levels of collaboration. Through this ecosystem, the Grand Alliance seeks to help both customers and alliance members accelerate innovation, reduce development costs, increase interoperability, and enable new architectures and systems, while ensuring TSMC's competitiveness in winning business.

The foundation for customer trust is a commitment TSMC made when it opened for business in 1987 to never compete with its customers. In keeping this commitment, the Company has never designed, manufactured or marketed any integrated circuits or IC devices under its own name, but instead has focused all of its efforts and resources on becoming the trusted foundry for its customers.

Strategy

TSMC is confident that its competitive advantages will enable it to prosper from the foundry segment's many attractive growth opportunities. For the five major markets, namely high performance computing, smartphones, the Internet of Things, automotive, and digital consumer electronics, and in response to the fact that the focus of customer demand is shifting from a process-technology-centric to a product-application-centric approach, the Company has constructed five corresponding technology platforms to provide customers with comprehensive, competitive logic process technologies, specialty technologies, IPs and packaging and testing technologies to shorten customers' time-to-design and time-to-market. These five platforms are:

High Performance Computing (HPC): Driven by data explosion and AI application innovation, HPC has become the key growth driver for TSMC's business. TSMC provides customers, including both fabless IC design companies and systems companies, with leading-edge logic process technologies such as 2nm nanosheet (N2), 3nm FinFET (N3), 4nm FinFET (N4), 5nm FinFET (N5), 6nm FinFET (N6), and 7nm FinFET (N7), as well as comprehensive IPs including high-speed interconnect IPs, to meet customers' product requirements for transferring and processing vast amounts of data anywhere at any time. Specifically, the Company introduced its HPC-focused technologies such as N4X, N3X, and N2X, representing the ultimate performance and maximum clock frequencies in TSMC's 5nm, 3nm, and 2nm families, respectively. Based on advanced process nodes, a variety of HPC products have been launched, such as AI accelerators, including AI GPUs and AI ASICs, PC CPUs, consumer GPUs, field programmable gate arrays (FPGAs), server processors, and high-speed networking chips, etc. These products can be used in current and future 5G/6G infrastructures, AI, cloud, and enterprise data centers. The Company also offers multiple TSMC 3DFabric® advanced silicon stacking and packaging solutions, such as TSMC-SoIC® manufacturing services and CoWoS® advanced packaging services, to enable homogeneous and heterogeneous chip integration to meet customer requirements for high performance, high compute density and high energy efficiency, low latency, and high integration. TSMC will continue to optimize its HPC platform and strengthen its collaboration with customers to help them capture market growth in HPC markets.

Smartphones: For customers' premium product applications, TSMC offers leading logic process technologies such as N2 Plus (N2P), N3 Plus (N3P), N3 Enhanced (N3E), N3, N4 Plus (N4P), N4, N5 Plus (N5P), N5, as well as comprehensive IPs to further enhance chip performance, reduce power consumption, and decrease chip size. For mainstream product applications, the Company provides a broad range of logic process technologies, including N3 Compact (N3C), N4 Compact (N4C), N6, 7nm FinFET Plus (N7+), N7, 12nm FinFET Compact Plus (12FFC+), 12nm FinFET Compact (12FFC), 16nm FinFET Compact Plus (16FFC+), 16nm FinFET Compact (16FFC), 28nm High Performance Compact Plus (28HPC+), 28nm High Performance Compact (28HPC), and 22nm Ultra-Low Power (22ULP), as well as comprehensive IPs, to satisfy customer needs for high-performance and low-power chips. Furthermore, for both premium and mainstream product applications, the Company offers leading-edge, highly competitive specialty technologies to deliver specialty companion chips for customers' logic application processors, including radio frequency (RF), RF front-end, embedded non-volatile memory (eNVM), power management ICs, sensors, and display chips, as well as TSMC 3DFabric® advanced packaging services, such as TSMC's industry-leading InFO technology.

Internet of Things (IoT): Following the three megatrends of the IoT segment, "Everything Connected, Smart and Green," TSMC not only provides customers with solid logic technologies, including 4nm, 5nm, 6nm, 7nm, 12nm, 16nm, and 28nm, but also builds a leading, complete and highly integrated ULP technology platform based on its logic technologies to enable customers' product innovations for the Artificial Intelligence of Things (AIoT) and Edge AI.

TSMC's industry-leading ULP technologies feature both energy efficiency and high performance, providing more computing power and AI inferencing capability while reducing system power consumption. FinFET-based 6nm technology service, N6e® ULP, and 12nm technology service, N12e® ULP, have both entered volume production, while the next-generation 4nm ULP technology is in development. In addition, planar transistor-based mainstream technologies, such as 22nm Ultra-Low Leakage (ULL), 28nm ULP, 40nm ULP, and 55nm ULP technologies, have been widely adopted by various IoT system-on-a-chip (SoC) and battery-powered products to extend battery life.

The Company's ULP technology platform also provides customers with comprehensive specialty technologies, covering RF, enhanced analog devices, embedded non-volatile memory, sensors, display devices, and PMICs. For extreme low-power product applications, TSMC has also extended its low operating voltage (Low Vdd) offerings and provided simulation program with integrated circuit emphasis (SPICE) models with a wide range of operating voltages and design guidelines to lower the adoption barrier and reduce lead time to help customers successfully launch innovative products.

Automotive: TSMC offers a comprehensive spectrum of technologies and services to support the automotive industry's three megatrends – building vehicles that are "Safer, Smarter and Greener." The Company is also an industry leader in providing a robust automotive IP ecosystem, which covers 3nm, 4nm, 5nm, 7nm, and 16nm FinFET technologies for ADAS, advanced in-vehicle infotainment (IVI), as well as zonal controllers for new electrical/electronic (E/E) architectures in next-generation vehicles, including both internal combustion engines (ICEs) and electric vehicles (EVs). N3A technology, based on N3E technology, is TSMC's most advanced automotive-grade technology to date and was released to customers at the end of 2025.

In addition to its advanced logic platform, TSMC offers comprehensive automotive-grade specialty technologies including 28nm embedded flash memory, 28nm, 22nm, and 16nm RF for mmWave applications, high dynamic range (HDR) and high sensitivity CMOS image sensors (CIS), light detection and ranging (LiDAR) sensors, and PMICs. As for magnetoresistive random-access memory (MRAM), the 16nm technology as second-generation MRAM passed Automotive Grade-1 requirements in 2025. 22ULL resistive random-access memory (RRAM) technology also passed Automotive Grade-1 requirements in 2025.

Digital Consumer Electronics (DCE): TSMC provides customers with leading comprehensive technologies to deliver superior performance for 8K/4K video streaming, AI features, better power efficiency, and seamless connectivity for DCE applications, including smart digital TVs (DTVs), set-top boxes (STBs), AI-embedded smart cameras and associated wireless local area networks (WLANs), and PMICs, etc. The Company's advanced N5, N7/N6, N16/N12, and 22ULP/22ULL technologies have been widely adopted by leading global makers of 8K/4K DTVs and STBs, 4K streaming media devices (SMDs)/over-the-top (OTT), digital single-lens reflex (DSLR) cameras, and so on. TSMC will continue to make these technologies more competitive through DTCO for customers' digital intensive chip designs and to drive lower power consumption for more cost-effective packaging.

TSMC continually strengthens its core competitiveness and deploys both short- and long-term plans for technology and business development in order to assist customers in tackling the challenges posed by short product cycles and intense competition in the electronic products market to achieve return on investment (ROI) and growth objectives.

- **Short-Term Semiconductor Business Development Plan**

1. Substantially ramp up the business and sustain advanced technology leadership by continually increasing capacity and R&D investments.
2. Maintain mainstream technology market segment share by expanding business to new customers and market segments.
3. Continue to enhance the competitive advantages of the Company's technology platforms in HPC, smartphones, IoT, automotive, and digital consumer electronics to expand TSMC's dedicated foundry services in these product applications.
4. Further expand TSMC's business and service infrastructure into emerging and developing markets.

- **Long-Term Semiconductor Business Development Plan**

1. Continue developing leading-edge technologies at a predictable pace to achieve greater energy-efficient computing.
2. Broaden specialty business contributions by further developing derivative technologies.
3. Provide more integrated services, covering system-level integration design, design technology definition, design tool preparation, wafer processing, TSMC 3DFabric® advanced silicon stacking and packaging solutions, backend packaging and testing services, etc., all of which deliver more value to customers through optimized solutions.

2.3 Board Members

2.3.1 Information Regarding Board Members

As of 02/28/2026

Title/Name	Gender Age	Nationality or Place of Registration	Date Elected	Term Expires	Date First Elected	Shares Held When Elected		Shares Currently Held		Shares Currently Held by Spouse & Minors		Selected Education and Professional Qualification Past Positions Current Positions at Non-profit Organizations	Selected Current Positions at TSMC and Other Companies
						Shares (Note 1)	%	Shares (Note 1)	%	Shares (Note 1)	%		
Chairman C.C. Wei	Male 71-75	R.O.C.	06/04/2024	06/03/2027	06/08/2017	6,392,834	0.02%	7,217,009	0.03%	700,261	0.00%	**Selected Education and Professional Qualification** Bachelor and Master Degrees in Electrical Engineering, National Chiao Tung University Ph.D. in Electrical Engineering, Yale University, U.S. Honorary Ph.D., National Yang Ming Chiao Tung University Laureate, Industrial Technology Research Institute (ITRI) **Past Positions** Senior Vice President, Technology, Chartered Semiconductor Manufacturing Ltd., Singapore Senior Vice President, Mainstream Technology Business, TSMC Senior Vice President, Business Development, TSMC Executive Vice President and Co-Chief Operating Officer, TSMC President and Co-CEO, TSMC Vice Chairman, TSMC Chairman, Taiwan Semiconductor Industry Association (TSIA)	Chief Executive Officer, TSMC
Director F.C. Tseng	Male 81-85	R.O.C.	06/04/2024	06/03/2027	05/13/1997	29,472,675	0.11%	29,472,675	0.11%	5,132,855	0.02%	**Selected Education and Professional Qualification** Bachelor Degree in Electrical Engineering, National Cheng Kung University Master Degree in Electrical Engineering, National Chiao Tung University Ph.D. in Electrical Engineering, National Cheng Kung University Honorary Ph.D., National Chiao Tung University Honorary Ph.D., National Tsing Hua University **Past Positions** President, Vanguard International Semiconductor Corp. President, TSMC Deputy CEO, TSMC Vice Chairman, TSMC Independent Director, Chairman of Audit Committee & Compensation Committee Member, Acer Inc. Director, National Culture and Arts Foundation, R.O.C. **Current Positions at Non-profit Organizations** Chairman, TSMC Education and Culture Foundation Director, Cloud Gate Culture and Arts Foundation Director, Jumin Medical Foundation	Chairman, TSMC China Company Ltd. (a non-public company) Chairman, Global UniChip Corp. Vice Chairman, Vanguard International Semiconductor Corp. Director, eMemory Technology, Inc.
Director National Development Fund, Executive Yuan (Note 2)			06/04/2024	06/03/2027	12/10/1986	1,653,709,980	6.38%	1,653,709,980	6.38%	-	-		
Representative: Chun-Hsien Yeh	Male 55-60	R.O.C.			09/01/2025 (Note 3)	-	-	-	-	-	-	**Selected Education and Professional Qualification** Ph.D. in Economics, University of Rochester, NY, U.S. Awarded Ta-You Wu Memorial Award Awarded 2011 and 2025 Outstanding Research Awards, Nation Science and Technology Council **Past Positions** Assistant Research Fellow, Institute of Economics, Academia Sinica Associate Professor, Department of Economics, National Central University Associate Research Fellow, Institute of Economics, Academia Sinica Vice President, Chung-Hua Institution for Economic Research Managing Director, Taiwan Business Bank President, Chung-Hua Institution for Economic Research Director, Taiwan Economic Associate **Current Positions at Non-profit Organizations** Research Fellow, Institute of Economics, Academia Sinica Minister without Portfolio, Executive Yuan & concurrently Minister, National Development Council The Convener of National Development Fund, Executive Yuan	Director, Taiwan Business Bank (Representative of the National Development Fund)

(Continued)

Title/Name	Gender Age	Nationality or Place of Registration	Date Elected	Term Expires	Date First Elected	Shares Held When Elected		Shares Currently Held		Shares Currently Held by Spouse & Minors		Selected Education and Professional Qualification Past Positions Current Positions at Non-profit Organizations	Selected Current Positions at TSMC and Other Companies
						Shares (Note 1)	%	Shares (Note 1)	%	Shares (Note 1)	%		
Independent Director Sir Peter L. Bonfield	Male 81-85	UK	06/04/2024	06/03/2027	05/07/2002	-	-	-	-	-	-	**Selected Education and Professional Qualification** Bachelor Degree in Engineering, Loughborough University Honorary Doctorate of Technology, Loughborough University Fellow of the Royal Academy of Engineering Knighted, 1996 Awarded Commander of the Order of the British Empire (CBE), 1989 Awarded the Order of the Lion of Finland Awarded the Gold Medal from the Institute of Management Awarded the Mountbatten Medal from the National Electronics Council Awarded the FT ODX Outstanding Director Award, 2019 11 Honorary Doctorate Degrees in total Awarded Commander of the Order of Orange Nassau, 2024 **Past Positions** Semiconductor Engineer, Texas Instruments Inc. (T.I.), U.S. Chairman, NXP Semiconductors N.V., the Netherlands Chairman and CEO, ICL Plc, UK CEO and Chairman of the Executive Committee, British Telecommunications Plc Chairman, GlobalLogic Inc., U.S. Vice President, the British Quality Foundation Director, Mentor Graphics Corp., U.S. Director, Sony Corp., Japan Director, L.M. Ericsson, Sweden Senior Independent Director, AstraZeneca, UK Chair of Council and Senior Pro-Chancellor, Loughborough University, UK Board Member, EastWest Institute, New York Senior Advisor, Alix Partners LLP, London Advisory Board Member, The Longreach Group Ltd., HK Member of the International Advisory Board, Citigroup, U.S. Board Mentor, Chairman Mentors International (CMi) Ltd., London Non-Executive Director, Darktrace Plc, UK	Non-Executive Director, Imagination Technologies Group Ltd., UK (a non-public company)
Independent Director Michael R. Splinter	Male 71-75	U.S.	06/04/2024	06/03/2027	06/09/2015	-	-	-	-	-	-	**Selected Education and Professional Qualification** Bachelor and Master Degrees in Electrical Engineering, University of Wisconsin-Madison Honorary Ph. D. in Engineering, University of Wisconsin-Madison Awarded 2013 Robert N. Noyce Award by Semiconductor Industry Association Member of the National Academy of Engineering Recognized as NACD (National Association of Corporate Directors) Directorship Certified™, 2020 **Past Positions** Executive Vice President of Technology and Manufacturing Group, Intel Corp. Executive Vice President of Sales and Marketing, Intel Corp. CEO, Applied Materials, Inc. Chairman, Applied Materials, Inc. Director, The NASDAQ OMX Group, Inc. Director, Silicon Valley Leadership Group Director, SEMI Director, Meyer Burger Technology Ltd., Switzerland Chairman of the Board, NASDAQ, Inc. Director, Pica8 Inc., U.S. Director, University of Wisconsin Foundation, U.S. Chairman of the Board, US-Taiwan Business Council Independent Director and Compensation Committee Chair, Gogoro Inc., Cayman Islands Chair of Industrial Advisory Committee, National Institute of Standards and Technology, Department of Commerce, U.S. Chair, Board of Trustees, Natcast, U.S.	Lead Independent Director, NASDAQ, Inc. Independent Director, Compensation Committee Chair, and Nominating and Corporate Governance Committee Member, Tigo Energy, Inc., U.S. Independent Director, Kioxia Holdings Corp., Japan General Partner, WISC Partners LP, U.S. General Partner, MRS Business and Technology Advisors, U.S. (a non-public company)
Independent Director Moshe N. Gavrielov	Male 71-75	U.S.	06/04/2024	06/03/2027	06/05/2019	-	-	-	-	-	-	**Selected Education and Professional Qualification** Bachelor Degree in Electrical Engineering, Technion - Israel Institute of Technology Master Degree in Computer Science, Technion - Israel Institute of Technology **Past Positions** In a variety of engineering and engineering management positions, National Semiconductor Corp. and Digital Equipment Corp., U.S. In a variety of executive management positions, LSI Logic Corp. for nearly 10 years, U.S. CEO, Verisity, Ltd., U.S. Executive Vice President and General Manager of the Verification Division, Cadence Design Systems, Inc., U.S. President and CEO, Xilinx, Inc., U.S. Director, Xilinx, Inc., U.S. Executive Chairman, Wind River Systems, Inc., U.S. Director, San Jose Institute of Contemporary Art, U.S. Advisor, Matrix Capital Management Company LP, U.S.	Chairman, SiMa Technologies, Inc., U.S. (a non-public company) Chairman, Foretellix, Ltd., Israel (a non-public company) Independent Director, NXP Semiconductors N.V., the Netherlands Independent Director, Cadence Design Systems, Inc., U.S.

(Continued)

Title/Name	Gender Age	Nationality or Place of Registration	Date Elected	Term Expires	Date First Elected	Shares Held When Elected		Shares Currently Held		Shares Currently Held by Spouse & Minors		Selected Education and Professional Qualification Past Positions Current Positions at Non-profit Organizations	Selected Current Positions at TSMC and Other Companies
						Shares (Note 1)	%	Shares (Note 1)	%	Shares (Note 1)	%		
Independent Director L. Rafael Reif	Male 71-75	U.S.	06/04/2024	06/03/2027	07/26/2021	-	-	-	-	-	-	**Selected Education and Professional Qualification** Ingeniero Eléctrico Degree, Universidad de Carabobo, Valencia, Venezuela Master Degree and Ph.D. in Electrical Engineering, Stanford University Honorary Doctor of Laws Degree, The Chinese University of Hong Kong (2015) Honorary Doctorates from Tsinghua University (2016), the Technion (2017), Arizona State University (2018) and University of Miami (2022) Member of Tau Beta Pi, the Engineering Honor Society Member of the Electrochemical Society Fellow of the Institute of Electrical and Electronics Engineers (IEEE) Member of the American Academy of Arts and Sciences, the National Academy of Engineering and the Chinese Academy of Engineering Fellow of the National Academy of Inventors Awarded with United States Presidential Young Investigator Award (1984) Awarded with the Semiconductor Research Corporation's Aristotle Award (2000) Awarded the Tribeca Disruptive Innovation Award (2012) Awarded the Frank E. Taplin, Jr. Public Intellectual Award by the Woodrow Wilson National Fellowship Foundation (2015) Awarded with Engineer of the Year from Great Minds in STEM (2018) Awarded the Simon Ramo Founders Award by the U.S. National Academy of Engineering (2022) Inventor or co-inventor on 13 patents, editor or co-editor of 5 books, and supervisor to 38 doctoral theses **Past Positions** Assistant Professor, Universidad Simón Bolívar, Caracas, Venezuela Visiting Assistant Professor of Electrical Engineering, Stanford University Faculty, Massachusetts Institute of Technology (MIT), since 1980 IBM Faculty Fellowship, MIT Center for Materials Science and Engineering Analog Devices Career Development Professorship, MIT Electrical Engineering Fariborz Maseeh Professor of Emerging Technology, MIT (2004-2012) Director of Microsystems Technology Laboratories, MIT Associate Department Head of Electrical Engineering, MIT Head of the Department of Electrical Engineering and Computer Science (EECS), MIT Provost, MIT Independent Director, Alcoa Corp., U.S. Director, Arconic Inc., U.S. Director, Schlumberger Ltd., U.S. President, MIT (2012-2022) Member, Board of Trustees, Massachusetts General Hospital, U.S. **Current Positions at Non-profit Organizations** President Emeritus, MIT, since 2023 Ray and Maria Stata Professor of Electrical Engineering and Computer Science, MIT, since 2023 Member, Board of Trustees, Carnegie Endowment for International Peace, U.S. Director, Council on Foreign Relations, U.S. Director, Waverley Street Foundation, U.S. Member, Board of Trustees, Instituto Tecnológico de Monterrey, Mexico	Co-Chair of Growth Technical Advisory Board, Applied Materials, Inc. Director, Engine No. 1 LP, U.S. (a non-public company)
Independent Director Ursula M. Burns	Female 66-70	U.S.	06/04/2024	06/03/2027	06/04/2024	-	-	-	-	-	-	**Selected Education and Professional Qualification** Bachelor Degree in Mechanical Engineering, Polytechnic Institute of New York University Master Degree in Mechanical Engineering, Columbia University Member, National Academy of Engineering Member, American Academy of Arts and Sciences Member, Royal Academy of Engineering **Past Positions** Chairwoman, CEO and President, Xerox Corp., U.S. Chairwoman and CEO, VEON Ltd., the Netherlands Director, American Express Company Director, Nestlé S.A., Switzerland Director, ExxonMobil Corp., U.S. Executive Chairwoman, Plum Acquisition Corp. I, U.S. Leader, White House National Program on Science, Technology, Engineering and Math (STEM) Chair, President's Export Council Member, G7 Gender Equality Advisory Council Director, Endeavor Group Holdings, Inc., U.S. Vice Chair, Advisory Council on Supply Chain Competitiveness (ACSCC), U.S. Department of Commerce **Current Positions at Non-profit Organizations** Member, Board of Trustees, Ford Foundation, U.S. Member, Board of Trustees, Massachusetts Institute of Technology (MIT) Corp. Member, Board of Trustees, Metropolitan Museum of Art, U.S. Member, Board of Trustees, Mayo Clinic, U.S. Member, Board of Trustees, Scratch Foundation, U.S. Member, Board of Trustees, The High Line, U.S. Member, Board of Trustees, FIRST, U.S. Member, Board of Trustees, NAF, U.S. Member, Board of Trustees, Columbia Engineering, U.S. Member, Board of Trustees, University of Rochester, U.S.	Non-Executive Chairwoman, Teneo Holdings LLC, U.S. (a non-public company) Independent Non-Executive Director, IHS Holding Ltd., Cayman Islands Director, Uber Technologies Inc., U.S. Director, Evertree Insurance Services, LLC, U.S. (a non-public company) Director, CleanCo Ventures Ltd., UK (a non-public company) Director, CardioSignal Inc., U.S. (a non-public company) Director, True Capital Partners, LLC, U.S. (a non-public company) Founding Partner, Integrum Holdings LP, U.S. (a non-public company)

(Continued)

Title/Name	Gender Age	Nationality or Place of Registration	Date Elected	Term Expires	Date First Elected	Shares Held When Elected		Shares Currently Held		Shares Currently Held by Spouse & Minors		Selected Education and Professional Qualification Past Positions Current Positions at Non-profit Organizations	Selected Current Positions at TSMC and Other Companies
						Shares (Note 1)	%	Shares (Note 1)	%	Shares (Note 1)	%		
Independent Director Lynn L. Elsenhans	Female 66-70	U.S.	06/04/2024	06/03/2027	06/04/2024	-	-	-	-	-	-	**Selected Education and Professional Qualification** Bachelor Degree in Applied Mathematics, Rice University Master Degree in Business Administration, Harvard University **Past Positions** Chairwoman, President and CEO, Sunoco Inc., U.S. Chairwoman and CEO, Sunoco Logistics Partners L.P., U.S. Executive Vice President of Global Manufacturing, Shell Downstream Inc., U.S. President and CEO, Shell Oil Products, U.S. President of Shell Oil Company and US Country Chair Independent Director, International Paper Company, U.S. Independent Director, Flowserve Corporation, U.S. Independent Director, GlaxoSmithKline plc, UK Audit Committee Chair, Saudi Arabian Oil Co., Kingdom of Saudi Arabia (2020-2024) **Current Positions at Non-profit Organizations** Advisory Board Member of Whiting School of Engineering, Johns Hopkins University	Independent Director and Governance & Corporate Responsibility Committee Chair, Baker Hughes Company, U.S. Independent Non-Executive Director, Audit Committee Member, and Nomination Committee Member, Saudi Arabian Oil Co., Kingdom of Saudi Arabia Independent Director, Peter Kiewit and Sons Inc., U.S. (a non-public company)
Independent Director Chuan Lin	Male 71-75	R.O.C.	06/04/2024	06/03/2027	06/04/2024	126,826	0.00%	126,826	0.00%	16,003	0.00%	**Selected Education and Professional Qualification** Bachelor Degree in Economics, Fu Jen Catholic University Master Degree in Public Finance, National Chengchi University Ph.D. in Economics, University of Illinois Urbana-Champaign, U.S. **Past Positions** Research Fellow, Chung-Hua Institution for Economic Research Professor and Department Chair, Public Finance, National Chengchi University Director General, Bureau of Finance, Taipei City Government Minister, Directorate General of Budget, Accounting and Statistics of Executive Yuan Minister of Finance Premier of Executive Yuan Chairman, Vanguard International Semiconductor Corporation Independent Director, Casetek Holdings Limited Independent Director, Inotera Memories, Inc. Director, PharmaEngine, Inc. Director, Chartis Taiwan Insurance Co., Ltd. Chief Executive Officer, New Frontier Foundation **Current Positions at Non-profit Organizations** Senior Advisor to the President	Chairman, TTY Biopharm Company Limited Chairman, TSH Biopharm Corporation Limited (Representative of TTY Biopharm Company Limited) Independent Director, Audit Committee Chair and Compensation Committee Member, Pegatron Corporation

Remarks:
1. No member of the Board of Directors held TSMC shares by nominee arrangement.
2. Managers or Directors who are spouses or within second-degree relative of consanguinity to the directors: None.
3. Rationale for electing the same person as Chairman and Chief Executive Officer (CEO): To navigate the rapidly changing landscape of the highly competitive semiconductor industry, TSMC's Board of Directors elected Dr. C.C. Wei as the Chairman and CEO following the Board's re-election at the Annual Shareholders' Meeting on June 4, 2024. With Dr. Wei at the helm, the alignment between the Board of Directors and the management team is expected to be more effective, enhancing efficiency in decision-making and execution and maximizing shareholder value. The Company currently has seven independent directors, accounting for 70% of the total board seats. The remaining directors do not hold managerial or employee roles within the Company, ensuring the Board's independence in decision-making while enabling professional oversight and guidance that meet shareholder and market expectations for the Company's stability and long-term value.

Note 1: Does not include shares held in the form of ADSs.
Note 2: Major Shareholders of the Institutional Shareholder

Institutional Shareholder	Major Shareholders (Top 10 Shareholders) of the Institutional Shareholder
National Development Fund, Executive Yuan	Not Applicable

Note 3: Dr. Chun-Hsien Yeh was appointed as the representative of the National Development Fund succeeding Mr. Chin-Ching Liu on September 1, 2025.

2.3.2 Remuneration of Directors and Independent Directors (Note 1)

Unit: NT$

Title/Name	Director's Remuneration								Sum of (A+B+C+D) and Ratio to Net Income		Compensation to a Director Who is an Employee of TSMC or of TSMC's Consolidated Entities								Sum of (A+B+C+D+E+F+G) and Ratio to Net Income (Note 6)		Compensation to Directors from Non-consolidated Affiliates or Parent Company
	Base Compensation (A)		Severance Pay and Pensions (B) (Note 3)		Compensation to Directors (C) (Note 4)		Allowances (D) (Note 5)				Base Compensation, Bonuses, and Allowances (E) (Note 5)		Severance Pay and Pensions (F) (Note 3)		Profit Sharing (G)						
															From TSMC		From All Consolidated Entities				
	From TSMC	From All Consolidated Entities	From TSMC	From All Consolidated Entities	From TSMC	From All Consolidated Entities	From TSMC	From All Consolidated Entities	From TSMC	From All Consolidated Entities	From TSMC	From All Consolidated Entities	From TSMC	From All Consolidated Entities	Cash	Stock (Fair Market Value)	Cash	Stock (Fair Market Value)	From TSMC	From All Consolidated Entities	
Chairman & Chief Executive Officer C.C. Wei	-	-	-	-	-	-	-	-	- -	- -	1,974,517,640	1,974,517,640	276,489	276,489	447,900,290	-	447,900,290	-	2,422,694,419 0.1410%	2,422,694,419 0.1410%	-
Director F.C. Tseng	-	-	-	-	12,144,000	12,144,000	1,061,305	1,061,305	13,205,305 0.0008%	13,205,305 0.0008%	-	-	-	-	-	-	-	-	13,205,305 0.0008%	13,205,305 0.0008%	18,591,667
Director National Development Fund, Executive Yuan Representative: Chun-Hsien Yeh (Note 2)	-	-	-	-	12,144,000	12,144,000	-	-	12,144,000 0.0007%	12,144,000 0.0007%	-	-	-	-	-	-	-	-	12,144,000 0.0007%	12,144,000 0.0007%	-
Independent Director Sir Peter L. Bonfield	-	-	-	-	18,859,632	18,859,632	-	-	18,859,632 0.0011%	18,859,632 0.0011%	-	-	-	-	-	-	-	-	18,859,632 0.0011%	18,859,632 0.0011%	-
Independent Director Michael R. Splinter	-	-	-	-	18,859,632	18,859,632	-	-	18,859,632 0.0011%	18,859,632 0.0011%	-	-	-	-	-	-	-	-	18,859,632 0.0011%	18,859,632 0.0011%	-
Independent Director Moshe N. Gavrielov	-	-	-	-	18,859,632	18,859,632	-	-	18,859,632 0.0011%	18,859,632 0.0011%	-	-	-	-	-	-	-	-	18,859,632 0.0011%	18,859,632 0.0011%	-
Independent Director L. Rafael Reif	-	-	-	-	18,859,632	18,859,632	-	-	18,859,632 0.0011%	18,859,632 0.0011%	-	-	-	-	-	-	-	-	18,859,632 0.0011%	18,859,632 0.0011%	-
Independent Director Ursula M. Burns	-	-	-	-	18,859,632	18,859,632	-	-	18,859,632 0.0011%	18,859,632 0.0011%	-	-	-	-	-	-	-	-	18,859,632 0.0011%	18,859,632 0.0011%	-
Independent Director Lynn L. Elsenhans	-	-	-	-	18,859,632	18,859,632	-	-	18,859,632 0.0011%	18,859,632 0.0011%	-	-	-	-	-	-	-	-	18,859,632 0.0011%	18,859,632 0.0011%	-
Independent Director Chuan Lin	-	-	-	-	18,859,632	18,859,632	-	-	18,859,632 0.0011%	18,859,632 0.0011%	-	-	-	-	-	-	-	-	18,859,632 0.0011%	18,859,632 0.0011%	-
Total	0	0	0	0	156,305,424	156,305,424	1,061,305	1,061,305	157,366,729 0.0092%	157,366,729 0.0092%	1,974,517,640	1,974,517,640	276,489	276,489	447,900,290	0	447,900,290	0	2,580,061,148 0.1502%	2,580,061,148 0.1502%	18,591,667

*Other than disclosure in the above table, Directors remunerations earned by providing services (e.g. providing consulting services as a non-employee of parent company/all consolidated entities/non-consolidated affiliates) to TSMC and all consolidated entities in the 2025 financial statements: Dr. F.C. Tseng for NT$19,891,747.

Note 1: Directors and Independent Directors' remuneration policies, procedures, standards and structure, as well as the linkage to responsibilities, risks and time spent:

1. According to TSMC's Articles of Incorporation, the Board of Directors is authorized to determine the salary for the Chairman, Vice Chairman and Directors, taking into account the extent and value of the services provided for the management of the Corporation and the standards of the industry within the R.O.C. and overseas.
2. The Articles of Incorporation also provide that the compensation to directors shall be no more than 0.3% of annual profits and directors who also serve as executive officers of TSMC are not entitled to receive compensation to directors. According to TSMC's Compensation and People Development Committee Charter, the distribution of compensation to directors shall be made in accordance with TSMC's "Rules for Distribution of Compensation to Directors" based on the following principles: (1) directors who also serve as executive officers of the Company are not entitled to receive compensation; and (2) the compensation for independent directors may be higher than other directors because they serve on multiple Committees, requiring their participation in discussions and resolutions according to each Committee's charter.

Note 2: Dr. Chun-Hsien Yeh was appointed as the representative of the National Development Fund succeeding Mr. Chin-Ching Liu on September 1, 2025.

Note 3: Pensions funded according to applicable law.

Note 4: The compensation of directors was expensed based on the estimated payment amounts. If the actual amounts subsequently paid differ from the above estimated amounts, the differences will be recorded in the year fully paid as a change in accounting estimate.

Note 5: The above-mentioned figures include expenses for Company cars and related reimbursements, but do not include compensation of Company drivers (totaled NT$6,971,338).

Note 6: Total remuneration of the directors from TSMC and from all consolidated entities in 2024, including their employee compensation, both accounted for 0.1239% of 2024 net income.

2.4 Management Team

2.4.1 Information Regarding Management Team

As of 02/28/2026

Title Name	Gender	Nationality	On-board Date (Note 1)	Shares Held		Shares Held by Spouse & Minors		Shares Held in the Name of Others		Education and Selected Past Positions	Selected Current Positions at Other Companies	Managers Who Are Spouses or within Second-degree Relative of Consanguinity to Each Other		
				Shares (Note 2)	%	Shares (Note 2)	%	Shares (Note 2)	%			Title	Name	Relation
C.C. Wei Chairman & Chief Executive Officer (Note 3)	Male	R.O.C.	02/01/1998	7,217,009	0.03%	700,261	0.00%	-	-	Ph.D., Electrical Engineering, Yale University, U.S. Chief Executive Officer, TSMC President and Co-Chief Executive Officer, TSMC Executive Vice President and Co-Chief Operating Officer, TSMC Senior Vice President, Business Development, TSMC Senior Vice President, Mainstream Technology Business, TSMC Senior Vice President, Chartered Semiconductor Manufacturing Ltd.	None	None	None	None
Y.P. Chyn Executive Vice President and Co-Chief Operating Officer Co-COO Office & Operations	Male	R.O.C.	01/01/1987	5,107,526	0.02%	4,190,107	0.02%	-	-	Master, Electrical Engineering, National Cheng Kung University, Taiwan Senior Vice President, Operations & Overseas Operations Office, TSMC Senior Vice President, Product Development, TSMC Vice President, Advanced Technology and Business, TSMC	Director, TSMC subsidiaries	None	None	None
Y.J. Mii Executive Vice President and Co-Chief Operating Officer Co-COO Office & Research and Development	Male	R.O.C.	11/14/1994	1,189,648	0.00%	-	-	-	-	Ph.D., Electrical Engineering, University of California, Los Angeles, U.S. Senior Vice President, Research and Development, TSMC Vice President, Technology Development, TSMC Senior Director, Platform I Division, TSMC	None	None	None	None
Cliff Hou Senior Vice President and Deputy Co-Chief Operating Officer Chief Information Security Officer	Male	R.O.C.	12/15/1997	597,994	0.00%	60,802	0.00%	-	-	Ph.D., Electrical Engineering, Syracuse University, U.S. Senior Vice President, Europe & Asia Sales and Research & Development/Corporate Research, TSMC Senior Vice President, Technology Development, TSMC Vice President, Design and Technology Platform, TSMC Senior Director, Design and Technology Platform, TSMC	Director, TSMC subsidiary	None	None	None
Kevin Zhang Senior Vice President and Deputy Co-Chief Operating Officer Business Development & Global Sales	Male	U.S.	11/01/2016	265,254	0.00%	-	-	-	-	Ph.D., Electrical Engineering, Duke University, U.S. Senior Vice President, Business Development & Overseas Operations Office, TSMC Vice President, Design and Technology Platform, TSMC Vice President, Technology and Manufacturing Group, Intel Corp.	None	None	None	None
Lora Ho Senior Vice President Corporate Strategy Development	Female	R.O.C.	06/01/1999	4,579,603	0.02%	2,039,530	0.01%	-	-	Master, Business Administration, National Taiwan University, Taiwan Senior Vice President, Human Resources, TSMC Senior Vice President, Europe and Asia Sales, TSMC Senior Vice President, Chief Financial Officer/ Spokesperson, TSMC Senior Director, Accounting, TSMC Vice President & CFO, TI-Acer Semiconductor Manufacturing Corp.	Director and/or Supervisor, TSMC subsidiaries	None	None	None
Sylvia Fang Senior Vice President and General Counsel Corporate Governance Officer Legal	Female	R.O.C.	03/20/1995	817,518	0.00%	67,906	0.00%	384,000	0.00%	Master, Comparative Law, School of Law, University of Iowa, U.S. Attorney-at-law, Taiwan Vice President and General Counsel Corporate Governance Officer, Legal, TSMC Associate General Counsel, TSMC Senior Associate, Taiwan International Patent and Law Office (TIPLO)	Director and/or Supervisor, TSMC subsidiaries	None	None	None
Wendell Huang Senior Vice President and Chief Financial Officer Spokesperson Finance	Male	R.O.C.	05/03/1999	1,770,669	0.01%	-	-	-	-	Master, Business Administration, Cornell University, U.S. Vice President and Chief Financial Officer, Finance, TSMC Deputy Chief Financial Officer, TSMC Senior Director, Finance Division, TSMC Vice President, Corporate Finance, ING Barings Vice President, Corporate Finance, Chase Manhattan Bank Vice President, Corporate Finance, Bankers Trust Company	Director, Supervisor, and/or President, TSMC subsidiaries Director, TSMC affiliate	None	None	None
Y.L. Wang Senior Vice President Operations/Fab Operations I (Note 4)	Male	R.O.C.	06/01/1992	321,518	0.00%	1,135,529	0.00%	-	-	Ph.D., Electrical Engineering, National Chiao Tung University, Taiwan Vice President, Fab Operations I, TSMC CEO, TSMC Arizona Vice President, Fab Operations, TSMC Vice President, Technology Development, TSMC Vice President, Fab 14B, TSMC Senior Director, Fab 14B, TSMC	None	None	None	None
T.S. Chang Senior Vice President and TSMC Senior Fellow Operations/Advanced Technology and Mask Engineering (Note 4, 5)	Male	R.O.C.	02/06/1995	276,764	0.00%	-	-	-	-	Ph.D., Electrical Engineering, National Tsing Hua University, Taiwan Vice President, Advanced Technology and Mask Engineering, TSMC Vice President, Product Development, TSMC Vice President, Fab 12B, TSMC Senior Director, Fab 12B, TSMC	None	None	None	None
Michael Wu Senior Vice President Research and Development/Platform Technology Research and Development/Technology Development Effectiveness Office (Note 4)	Male	R.O.C.	12/09/1996	589,354	0.00%	198,943	0.00%	-	-	Ph.D., Electrical Engineering, University of Wisconsin-Madison, U.S. Vice President, Platform Development/Technology Development Effectiveness Office, TSMC Senior Director, Platform Development, TSMC	None	None	None	None
Geoffrey Yeap Senior Vice President Research and Development/Platform Technology (Note 4)	Male	U.S.	03/21/2016	175,694	0.00%	-	-	-	-	Ph.D., Electrical and Computer Engineering, University of Texas-Austin, U.S. Vice President, Platform Development, TSMC Senior Director, Platform Development, TSMC Senior Director, Advanced Technology, TSMC Vice President, Engineering, Silicon Technology, Qualcomm	None	None	None	None
Min Cao Vice President Research and Development/Corporate Research Research and Development/Pathfinding	Male	U.S.	07/29/2002	467,005	0.00%	34,470	0.00%	-	-	Ph.D., Physics, Stanford University, U.S. Senior Director, Pathfinding Division, TSMC	None	None	None	None

(Continued)

Title Name	Gender	Nationality	On-board Date (Note 1)	Shares Held		Shares Held by Spouse & Minors		Shares Held in the Name of Others		Education and Selected Past Positions	Selected Current Positions at Other Companies	Managers Who Are Spouses or within Second-degree Relative of Consanguinity to Each Other		
				Shares (Note 2)	%	Shares (Note 2)	%	Shares (Note 2)	%			Title	Name	Relation
Y.H. Liaw Vice President Operations/Fab Operations II CEO JASM	Male	R.O.C.	08/03/1988	437,044	0.00%	-	-	430,000	0.00%	Master, Chemical Engineering, National Tsing Hua University, Taiwan Vice President, Fab Operations, TSMC Vice President, Fab 15B, TSMC Senior Director, Fab 15B, TSMC	Director, TSMC subsidiaries Director, TSMC affiliate	None	None	None
Simon Jang Vice President Research and Development/Advanced Tool and Module Development	Male	R.O.C.	09/01/1993	417,869	0.00%	2,000	0.00%	-	-	Ph.D., Materials Science & Engineering, Massachusetts Institute of Technology, U.S. Senior Director, Advanced Tool and Module Development Division, TSMC	None	Deputy Director	Sharon Jang	Sister
C.S. Yoo Vice President Research and Development/Specialty	Male	R.O.C.	06/16/1988	1,771,604	0.01%	219,924	0.00%	851,908	0.00%	Ph.D., Chemical Engineering, Worcester Polytech. Institute, U.S. Vice President, Europe & Asia Sales, TSMC Senior Director, Office of Strategy Customer Program, TSMC Senior Director, E-Beam Operation Division, TSMC	Director, TSMC affiliate	None	None	None
Jun He Vice President Operations/Advanced Packaging Technology and Service	Male	R.O.C.	05/22/2017	94,109	0.00%	-	-	-	-	Ph.D., Materials Science and Engineering, University of California, Santa Barbara, U.S. Vice President, Quality and Reliability, TSMC Senior Director, Quality and Reliability, TSMC Senior Director, Head of Quality and Reliability for Technology & Manufacturing Group, Intel Corp.	Director, TSMC subsidiary	None	None	None
Chris Horng-Dar Lin Vice President and Chief Information Officer Corporate Information Technology	Male	U.S.	01/04/2021	102,174	0.00%	15,000	0.00%	-	-	Ph.D., Electrical Engineering and Computer Science, University of California, Berkeley, U.S. Vice President, Information Technology, Mozilla Director, Enterprise Platform Infrastructure, Facebook	None	None	None	None
Jonathan Lee Vice President Corporate Planning Organization	Male	R.O.C.	05/28/2007	480,022	0.00%	6,000	0.00%	-	-	Master, Business Administration, City University of New York, Baruch College, U.S. Senior Director, Strategic Planning Division, TSMC	None	None	None	None
Arthur Chuang Vice President Operations/Facility	Male	R.O.C.	01/17/1989	2,669,155	0.01%	1,993,140	0.01%	-	-	Ph.D., Civil Engineering, National Taiwan University, Taiwan Senior Director, Facility Division, TSMC	Director, TSMC subsidiary	Technical Manager	Gavin Chuang	Brother
L.C. Lu Vice President and TSMC Senior Fellow Research and Development/Design & Technology Platform (Note 5)	Male	R.O.C.	08/01/2000	245,706	0.00%	15,000	0.00%	-	-	Ph.D., Computer Science, Yale University, U.S. Senior Director, Digital IPs Solution Division, TSMC	Director, and/or President, TSMC subsidiaries	None	None	None
K.C. Hsu Vice President Research and Development/Integrated Interconnect & Packaging	Male	R.O.C.	11/01/2021	152,914	0.00%	10,000	0.00%	-	-	Master, Technology Management, National Chiao-Tung University, Taiwan Taiwan Country Manager, Micron Technology Inc. President, WaferTech LLC	None	None	None	None
Ray Chuang Vice President Operations/Fab Operations I CEO TSMC AZ (Note 6)	Male	R.O.C.	12/15/1997	224,875	0.00%	106,000	0.00%	-	-	Master, Materials Science & Engineering/Engineering Economics System, Stanford University, U.S. Managing Director, ESMC Senior Director, Fab 18A, TSMC Director, Fab 12B, TSMC	Director, TSMC subsidiary	None	None	None
P.H. Chen Vice President Human Resources	Male	R.O.C.	08/01/1990	433,414	0.00%	83,143	0.00%	-	-	Master, Chemistry, National Sun Yat-sen University, Taiwan Senior Director, Program Office, TSMC Senior Fab Director, Fab 14A, TSMC	None	None	None	None
Y.K. Hwang Vice President Materials Management (Note 7)	Male	R.O.C.	07/17/1995	206,418	0.00%	-	-	-	-	Master, Business Administration, University of Texas-Arlington, U.S. Senior Director, Materials Management, TSMC Senior Fab Director, Fab 18B, TSMC Fab Director, Fab 18B, TSMC	None	None	None	None
B.Z. Tien Vice President Operations/ Fab 12B (Note 7)	Male	R.O.C.	02/02/1998	5,051	0.00%	-	-	-	-	Master, Electronics Engineering, National Chiao-Tung University, Taiwan Senior Fab Director, Fab 12B, TSMC Fab Director, Fab 12B, TSMC	None	None	None	None
S.S. Lin Vice President Research & Development/ Platform Technology (Note 7)	Male	R.O.C.	10/16/2000	20,269	0.00%	-	-	-	-	Ph.D., Electrical & Computer Engineering, National Chiao Tung University, Taiwan Senior Director, Platform Technology, TSMC Senior Director, Integration Division, TSMC Senior Director, Platform Development Division, TSMC Director, Platform Development Division, TSMC	None	None	None	None
Lipen Yuan Vice President Advanced Technology Business Development (Note 7)	Male	R.O.C.	08/01/2011	2,000	0.00%	1,600	0.00%	-	-	Ph.D., Electrical & Computer Engineering, University of Illinois Urbana-Champaign, U.S. Senior Director, Advanced Technology Business Development, TSMC Director, Advanced Technology Business Development, TSMC Director, Director of Design Solution Exploration & Tech Benchmarking Division, TSMC	None	None	None	None

Note 1: On-board date means the official date joining TSMC.
Note 2: Dose not include shares held in the form of ADSs.
Note 3: Rationale for electing the same person as Chief Executive Officer (CEO) and Chairman: To navigate the rapidly changing landscape of the highly competitive semiconductor industry, TSMC's Board of Directors elected Dr. C.C. Wei as the Chairman and CEO following the Board's re-election at the Annual Shareholders' Meeting on June 4, 2024. With Dr. Wei at the helm, the alignment between the Board of Directors and the management team is expected to be more effective, enhancing efficiency in decision-making and execution and maximizing shareholder value. The Company currently has seven independent directors, accounting for 70% of the total board seats. The remaining directors do not hold managerial or employee roles within the Company, ensuring the Board's independence in decision-making while enabling professional oversight and guidance that meet shareholder and market expectations for the Company's stability and long-term value.
Note 4: Dr. Y.L. Wang, Dr. T.S. Chang, Dr. Michael Wu, and Dr. Geoffrey Yeap were promoted to Senior Vice President, effective February 10, 2026.
Note 5: Dr. T.S. Chang and Dr. L.C. Lu were promoted to TSMC Senior Fellow, effective June 17, 2025.
Note 6: Mr. Ray Chuang was appointed as CEO of TSMC Arizona, effective October 1, 2025.
Note 7: Mr. Y.K. Hwang, Mr. B.Z. Tien, Dr. S.S. Lin, and Dr. Lipen Yuan were promoted to Vice President, effective February 10, 2026.

2.4.2 Compensation of CEO and Vice Presidents (Note 1)

Unit: NT$

Title	Name	Salary (A)		Severance Pay and Pensions (B) (Note 6)		Bonuses and Allowances (C) (Note 7)		Profit Sharing (D)				Sum of (A+B+C+D) and Ratio to Net Income (Note 8)		Compensation from Non-consolidated Affiliates or Parent Company
								From TSMC		From All Consolidated Entities				
		From TSMC	From All Consolidated Entities	From TSMC	From All Consolidated Entities	From TSMC	From All Consolidated Entities	Cash	Stock (Fair Market Value)	Cash	Stock (Fair Market Value)	From TSMC	From All Consolidated Entities	
Chairman & Chief Executive Officer	C.C. Wei	17,280,600	17,280,600	276,489	276,489	1,957,237,040	1,957,237,040	447,900,290	-	447,900,290	-	2,422,694,419 0.1410%	2,422,694,419 0.1410%	-
Senior Vice President, Chief Financial Officer/Spokesperson	Wendell Huang	6,794,603	6,794,603	108,712	108,712	229,138,027	229,138,027	103,474,760	-	103,474,760	-	339,516,102 0.0198%	339,516,102 0.0198%	-
Executive Vice President and Co-Chief Operating Officer	Y.P. Chyn	147,605,603	174,505,400	2,361,693	2,884,272	4,156,166,932	4,306,705,897	1,813,719,990	-	1,813,719,990	-	6,119,854,218 0.3562%	6,297,815,559 0.3666%	-
Executive Vice President and Co-Chief Operating Officer	Y.J. Mii													
Senior Vice President and Deputy Co-Chief Operating Officer/Chief Information Security Officer	Cliff Hou													
Senior Vice President and Deputy Co-Chief Operating Officer	Kevin Zhang													
Senior Vice President	Lora Ho													
Senior Vice President	Wei-Jen Lo (Note 2)													
Executive Consultant	Rick Cassidy (Note 2)													
Senior Vice President/Former Chief Information Security Officer	J.K. Lin (Note 2)													
Senior Vice President and General Counsel/Corporate Governance Officer	Sylvia Fang													
Senior Vice President	Y.L. Wang (Note 3)													
Senior Vice President and TSMC Senior Fellow	T.S. Chang (Note 3, 4)													
Senior Vice President	Michael Wu (Note 3)													
Senior Vice President	Geoffrey Yeap (Note 3)													
Vice President and TSMC Distinguished Fellow	Douglas Yu (Note 2)													
Vice President	Min Cao													
Vice President/CEO, JASM	Y.H. Liaw													
Vice President	Simon Jang													
Vice President	C.S. Yoo													
Vice President	Jun He													
Vice President and Chief Information Officer	Chris Horng-Dar Lin													
Vice President	Jonathan Lee													
Vice President	Arthur Chuang													
Vice President and TSMC Senior Fellow	L.C. Lu (Note 4)													
Vice President	K.C. Hsu													
Vice President/CEO, TSMC Arizona	Ray Chuang													
Vice President	Vanessa Lee (Note 2)													
Vice President	P.H. Chen (Note 5)													
Total		171,680,806	198,580,603	2,746,894	3,269,473	6,342,541,999	6,493,080,964	2,365,095,040	0	2,365,095,040	0	8,882,064,739 0.5170%	9,060,026,080 0.5274%	0

Note 1: The total compensation of the executive officers is based on their job responsibility, contribution, company performance, and effective risk management. This includes traditional financial measures like company performance (revenue growth, return on equity, alongside risk-indicators). By maintaining a balanced perspective, the company is committed to achieve sustainable growth and risk-conscious performance. It is reviewed by the Compensation and People Development Committee then submitted to the Board of Directors for approval.

Note 2: Senior Vice President Mr. J.K. Lin retired, effective April 10, 2025. Senior Vice President Mr. Rick Cassidy changed his job responsibility to Executive Consultant, effective July 1, 2025. Vice President Dr. Douglas Yu retired, effective July 8, 2025. Vice President Ms. Vanessa Lee resigned, effective July 13, 2025. Senior Vice President Dr. Wei-Jen Lo retired, effective July 27, 2025.

Note 3: Dr. Y.L. Wang, Dr. T.S. Chang, Dr. Michael Wu, and Dr. Geoffrey Yeap were promoted to Senior Vice President, effective February 10, 2026.

Note 4: Dr. T.S. Chang and Dr. L.C. Lu were promoted to TSMC Senior Fellow, effective June 17, 2025.

Note 5: Mr. P.H. Chen was promoted to Vice President, effective February 12, 2025. These amounts did not include compensation for the period before his promotion.

Note 6: Pensions funded according to applicable law.

Note 7: The above-mentioned figures include the expense for the business performance bonuses distributed in May, August, November 2025 & February 2026, and Company cars and gasoline reimbursements.

Note 8: Total compensation of the executive officers from TSMC in 2024 accounted for 0.4330% of 2024 net income. Total compensation of the executive officers from all consolidated entities in 2024 accounted for 0.4516% of 2024 net income.

The Company's Policy, Standards/Packages, Procedures for the Compensation of the CEO and Vice Presidents, and the Linkage to Their Performance Evaluation and the Future Risk Exposure:

• The Company's Policy, Standards/Packages

The compensation of the CEO and Vice Presidents takes into account, in a comprehensive manner, aspects of their experience, professional capabilities, managerial skills, and the positions they hold. The said compensation is also closely linked to both the financial and non-financial performance goals, so as to reflect the fulfillment of their responsibilities as well as their work performance. Compensation includes salary, quarterly paid cash bonus, allowances, and profit sharing based on annual profits of the Company. Moreover, since 2021, TSMC has begun to offer Employee Restricted Stock Awards to link their compensation with shareholders' interests and ESG achievements. The company places a greater emphasis on variable compensation constituting a larger proportion of the total compensation versus fixed compensation, and prioritizes long-term incentive rewards to better align the compensation of our CEO and executives with the company's sustainable business performance, shareholder interests, and ESG achievements. The Compensation and People Development Committee approves the compensation plan regularly, which is then submitted to the Board of Directors for approval.

• The Procedures

Quarterly cash bonuses and profit-sharing are for the purpose of rewarding employee contributions, incentivizing employees to continue to work hard, and aligning employee interests with those of TSMC's shareholders. According to Articles of Incorporation, if the Company is profitable for the year, at least 1% of the profits will be allocated as employee compensation. The frequency, date, and conditions of the distribution of employee compensation will be determined according to the Company's bonus policy. The Company further determines the bonus and profit-sharing amounts based on operating results and common domestic industry practice. The amount and distribution of the employee bonuses are recommended by the Compensation and People Development Committee to the Board of Directors for approval. Cash bonuses are paid quarterly, and profit sharing are paid after approval at the Board of Directors meeting and having reported the same at the Shareholders' meeting.

TSMC established Employee Restricted Stock Awards to link the compensation for CEO and Vice Presidents with ESG achievements and the interests of shareholders. The number of shares granted to the CEO and Vice Presidents will be determined by the Chairman and CEO by taking into account the Company's business performance, the individual's job grade, performance, and other factors as deemed appropriate and approved by Compensation and People Development Committee, and ultimately subject to Board of Directors' approval.

• The Linkage to The Performance Evaluation

The compensation of TSMC's CEO and Vice Presidents is governed by the Company's bonus policy, which covers the achievement of both corporate operational goals and personal annual objectives. Corporate goals include financial indicators and non-financial indicators. Personal annual objectives include operational goals and ESG achievements in focus areas: Drive Green Manufacturing, Build a Sustainable Supply Chain, Create a Diverse and Inclusive Workplace, Develop Talent, and Care for the Disadvantaged. The Employee Restricted Stock Awards provided has a vesting period of three years (for details, please refer to "4.6.1 Status of Employee Restricted Stock" on pages 86-93 of this Annual Report). The corporate performance indicators are the relative total shareholder return (TSR) of the company compared to TSR of the S&P 500 IT Index, with the company's ESG achievements as a modifier. Effective in 2025, TSMC adopted an annual Long-Term Incentive (LTI) bonus plan to attract and retain corporate executives and critical talent. Eligible participants will receive bonuses, tied to a set of performance metrics. These metrics include individual annual performance, company financial indicators (Revenue Growth Rate, Gross Margin, Return on Equity), company TSR performance relative to a peer group, and company ESG achievements. Through these diverse and clear quantitative indicators, we strengthen management's long-term and continuous creation of company revenue and shareholder value while improving ESG performance towards target achievement, which shows a strong correlation with the Company's overall operating performance.

• The Future Risk Exposure

The compensation of TSMC's CEO and Vice Presidents is based on the relevant industry benchmarks and the performance of the Company. The standards, structure, and system of compensation are reviewed and adjusted as necessary in response to changes in the Company's actual operating conditions and relevant laws and regulations. The Company's financial incentive programs are tied to meeting risk-related goals and the pursue of Company's objectives are within the Company's risk appetite and tolerance.

• Clawback Policy

TSMC established the Clawback policy in 2023. (Disclosed on tsmc.com/Home /Investors/Corporate Governance/Major Internal Policies/TSMC Clawback Policy)

Compensation of CEO and Vice Presidents

	2025	
	From TSMC	From All Consolidated Entities and Non-consolidated Affiliates
NT$0 ~ NT$999,999	Rick Cassidy	None
NT$1,000,000 ~ NT$1,999,999	None	None
NT$2,000,000 ~ NT$3,499,999	None	None
NT$3,500,000 ~ NT$4,999,999	None	None
NT$5,000,000 ~ NT$9,999,999	None	None
NT$10,000,000 ~ NT$14,999,999	None	None
NT$15,000,000 ~ NT$29,999,999	None	None
NT$30,000,000 ~ NT$49,999,999	Vanessa Lee	Vanessa Lee
NT$50,000,000 ~ NT$99,999,999	None	None
Over NT$100,000,000	C.C. Wei, Wendell Huang, Y.P. Chyn, Y.J. Mii, Cliff Hou, Kevin Zhang, Lora Ho, Wei-Jen Lo, J.K. Lin, Sylvia Fang, Y.L. Wang, Douglas Yu, T.S. Chang, Michael Wu, Min Cao, Y.H. Liaw, C.S. Yoo, Jun He, Geoffrey Yeap, Jonathan Lee, Arthur Chuang, L.C. Lu, K.C. Hsu, Simon Jang, Chris Horng-Dar Lin, Ray Chuang, P.H. Chen	C.C. Wei, Wendell Huang, Y.P. Chyn, Y.J. Mii, Cliff Hou, Kevin Zhang, Lora Ho, Wei-Jen Lo, Rick Cassidy, J.K. Lin, Sylvia Fang, Y.L. Wang, Douglas Yu, T.S. Chang, Michael Wu, Min Cao, Y.H. Liaw, C.S. Yoo, Jun He, Geoffrey Yeap, Jonathan Lee, Arthur Chuang, L.C. Lu, K.C. Hsu, Simon Jang, Chris Horng-Dar Lin, Ray Chuang, P.H. Chen
Total	29	29

2.4.3 Employees' Profit Sharing of Management Team

Unit: NT$

Title	Name	Stock (Fair Market Value)	Cash	Total	Total Profit Sharing of Management Team as a % of Net Income
Chairman & Chief Executive Officer	C.C. Wei	-	447,900,290	447,900,290	0.0261%
Senior Vice President, Chief Financial Officer/Spokesperson	Wendell Huang	-	103,474,760	103,474,760	0.0060%
Executive Vice President and Co-Chief Operating Officer	Y.P. Chyn				
Executive Vice President and Co-Chief Operating Officer	Y.J. Mii				
Senior Vice President and Deputy Co-Chief Operating Officer/Chief Information Security Officer	Cliff Hou				
Senior Vice President and Deputy Co-Chief Operating Officer	Kevin Zhang				
Senior Vice President	Lora Ho				
Senior Vice President	Wei-Jen Lo (Note 1)				
Executive Consultant	Rick Cassidy (Note 1)				
Senior Vice President/Former Chief Information Security Officer	J.K. Lin (Note 1)				
Senior Vice President and General Counsel/Corporate Governance Officer	Sylvia Fang				
Senior Vice President	Y.L. Wang (Note 2)				
Senior Vice President and TSMC Senior Fellow	T.S. Chang (Note 2, 3)				
Senior Vice President	Michael Wu (Note 2)				
Senior Vice President	Geoffrey Yeap (Note 2)				
Vice President and TSMC Distinguished Fellow	Douglas Yu (Note 1)	-	1,813,719,990	1,813,719,990	0.1056%
Vice President	Min Cao				
Vice President/CEO, JASM	Y.H. Liaw				
Vice President	Simon Jang				
Vice President	C.S. Yoo				
Vice President	Jun He				
Vice President and Chief Information Officer	Chris Horng-Dar Lin				
Vice President	Jonathan Lee				
Vice President	Arthur Chuang				
Vice President and TSMC Senior Fellow	L.C. Lu (Note 3)				
Vice President	K.C. Hsu				
Vice President/CEO, TSMC Arizona	Ray Chuang				
Vice President	Vanessa Lee (Note 1)				
Vice President	P.H. Chen (Note 4)				
Total		0	2,365,095,040	2,365,095,040	0.1377%

Note 1: Senior Vice President Mr. J.K. Lin retired, effective April 10, 2025. Senior Vice President Mr. Rick Cassidy changed his job responsibility to Executive Consultant, effective July 1, 2025. Vice President Dr. Douglas Yu retired, effective July 8, 2025. Vice President Ms. Vanessa Lee resigned, effective July 12, 2025. Senior Vice President Dr. Wei-Jen Lo retired, effective July 27, 2025.
Note 2: Dr. Y.L. Wang, Dr. T.S. Chang, Dr. Michael Wu, and Dr. Geoffrey Yeap were promoted to Senior Vice President, effective February 10, 2026.
Note 3: Dr. T.S. Chang and Dr. L.C. Lu were promoted to TSMC Senior Fellow, effective June 17, 2025.
Note 4: Mr. P.H. Chen was promoted to Vice President, effective February 12, 2025. These amounts did not include compensation for the period before his promotion.